

WHAT IS CLAIMED IS:

1. A method for manufacturing a semiconductor device, including the steps of:

5 providing a substrate having first and second main surfaces and having a semiconductor element formed in the first main surface;

10 forming a first groove in the first main surface of the substrate, the first groove having a bottom surface with a width and opposing side surfaces on the bottom surface;

forming selectively a catalyst layer on the bottom surface of the first groove, the catalyst layer containing palladium in an upper surface thereof;

15 forming a first metal layer of a nickel based plating layer on the upper surface of the catalyst layer by an electroless plating technique, a top portion of the first metal layer located at a distance below a top end of the side surface of the first groove;

20 forming a second groove in the second main surface of the substrate along the first groove, the second groove having a bottom with a smaller width than that of the bottom of the first groove and opposing side surfaces on the bottom surface, the bottom surface of the second groove being a backside surface of the catalyst layer;

25 forming a second metal layer overlying the bottom

and side surfaces of the second groove; and

laser-cutting the first metal layer, the catalyst layer, and the second metal layer through the first groove.

2. A method for manufacturing a semiconductor device according to claim 1, after the step of forming the first metal layer further comprising the step of:

attaching a supporting member on the first main surface, and thinning the substrate through the second main surface.

3. A method for manufacturing a semiconductor device according to claim 1, wherein the step of forming the catalyst layer containing the steps of:

forming a first photoresist layer on the first surface of the substrate, the photoresist layer having an opening opposing to the first groove;

depositing a catalyst material on the bottom surface of the first groove through the first photoresist layer as a mask by evaporation or sputtering deposition; and

removing the first photoresist layer together with the catalyst material on the photoresist layer, and remaining the catalyst material on the bottom surface of the first groove.

4. A method for manufacturing a semiconductor device according to claim 1, wherein the catalyst layer has

two-layers of a palladium layer and a titanium layer under the palladium layer, or a single palladium layer.

5 5. A method for manufacturing a semiconductor device according to claim 1, wherein the nickel based plating layer is made of one material selected from Ni-P alloy, Ni-B alloy, and Ni-B-W alloy.

6. A semiconductor device comprising:

10 a semiconductor substrate having first and second main surfaces, having a semiconductor element formed in the first main surface and having a peripheral surface containing the first and second main surface;

10 sub- 6/10 a heat radiation layer provided on the second main surface of the semiconductor substrate; and

15 a flange of a plurality of metal layers disposed on the peripheral surface of the substrate, the metal layers comprising;

a first metal layer having a surface layer containing palladium on the same side with the first main surface,

20 a second metal layer of nickel based alloy disposed on the surface layer containing palladium of the first metal layer, and the second metal layer having a top portion located at a distance below the first main surface, and

25 a third metal layer disposed under the first



metal layer.

7. A semiconductor device according to claim 6,  
wherein the third metal layer comprises a nickel based  
alloy layer, a gold layer and a laser-cut metal layer  
5 including a nickel layer or a chromium layer.

*Sub.  
610  
PMD.*  
8. A semiconductor device according to claim 7,  
wherein the third metal layer further comprises a single  
layer of gold or a plurality of layers including a titanium  
layer and a gold layer on the laser-cut metal layer.

10 9. A semiconductor device according to claim 6,  
wherein the first metal layer comprises two-layers of a  
palladium layer and a titanium layer under the palladium  
layer, or a single layer.

15 10. A semiconductor device according to claim 6,  
wherein the second metal layer is made of one material  
selected from Ni-P alloy, Ni-B alloy, and Ni-B-W alloy.

---